



Features

- ✧ Glass passivated junction chip
- ✧ For surface mounted application
- ✧ Low profile package
- ✧ Built-in strain relief
- ✧ Ideal for automated placement
- ✧ Easy pick and place
- ✧ Ultrafast recovery time for high efficiency
- ✧ Low forward voltage, low power loss
- ✧ High temperature soldering guaranteed:
260°C/10 seconds on terminals
- ✧ Plastic material used carries Underwriters
Laboratory Classification 94V0

Mechanical Data

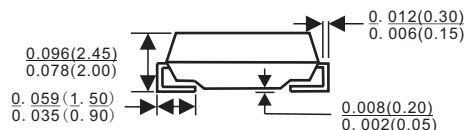
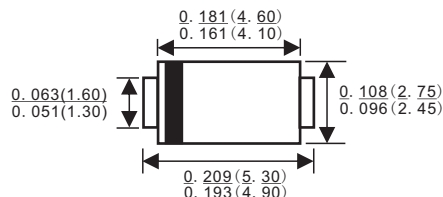
- ✧ Cases: Molded plastic
- ✧ Polarity: Indicated by cathode band
- ✧ Weight: 0.064 gram

Marking Information



LGE: Lu Guang Electronic
XXXX: marking code (US1A-US1M)

SMA/DO-214AC



Dimensions in inches and(millimeters)

Maximum Ratings and Electrical Characteristics

Rating at 25 °C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20%

Type Number	Symbol	US1A	US1B	US1D	US1G	US1J	US1K	US1M	Units
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current @ T _L =110 °C	I _(AV)	1.0							A
Peak Forward Surge Current, 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	30							A
Maximum Instantaneous Forward Voltage @ 1.0A	V _F	1.0				1.7			V
Maximum DC Reverse Current @ T _A =25 °C at Rated DC Blocking Voltage @ T _A =125 °C	I _R	5.0 150							uA uA
Maximum Reverse Recovery Time (Note 1)	T _{rr}	50				75			nS
Typical Junction Capacitance (Note 2)	C _j	15				10			pF
Maximum Thermal Resistance (Note 3)	R _{θJA} R _{θJL}	75 27							°C/W
Operating Temperature Range	T _J	-55 to +150							°C
Storage Temperature Range	T _{STG}	-55 to + 150							°C

- Notes:
1. Reverse Recovery Test Conditions: $I_F=0.5A$, $I_R=1.0A$, $I_{RR}=0.25A$
 2. Measured at 1 MHz and Applied $V_R=4.0$ Volts
 3. P.C.B. Mounted on 0.2 x 0.2" (5.0 x 5.0mm) Copper Pad Area.

RATINGS AND CHARACTERISTIC CURVES (US1A THRU US1M)

FIG.1- MAXIMUM FORWARD CURRENT DERATING CURVE

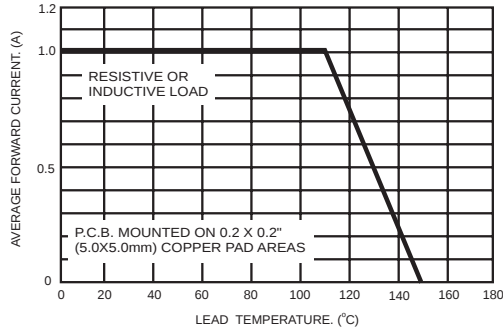


FIG.2- MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

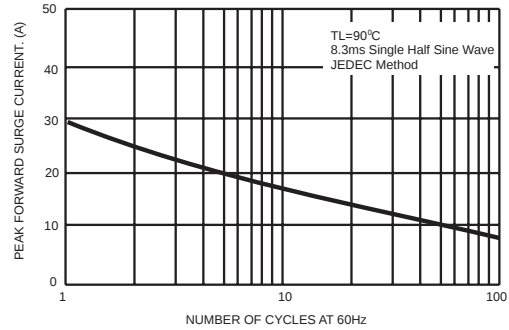


FIG.3- TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

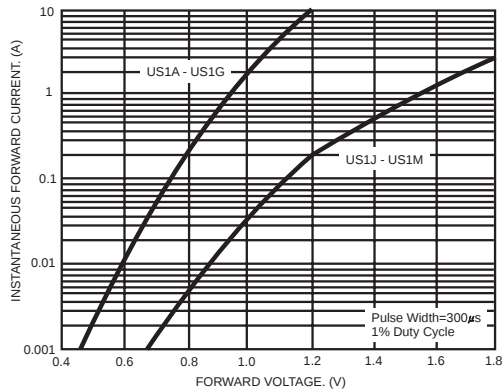


FIG.4- TYPICAL REVERSE CHARACTERISTICS

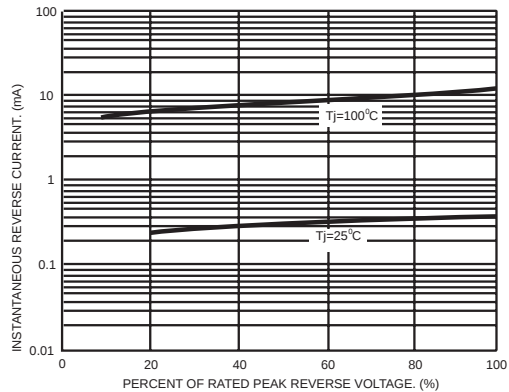


FIG.5- TYPICAL JUNCTION CAPACITANCE

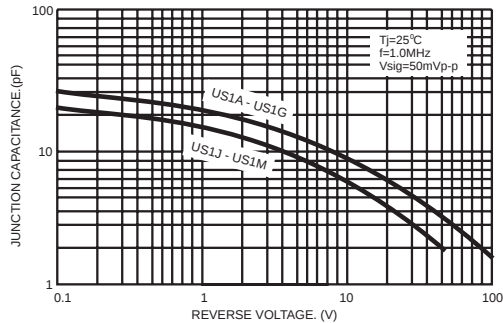


FIG.6- TYPICAL TRANSIENT THERMAL IMPEDANCE

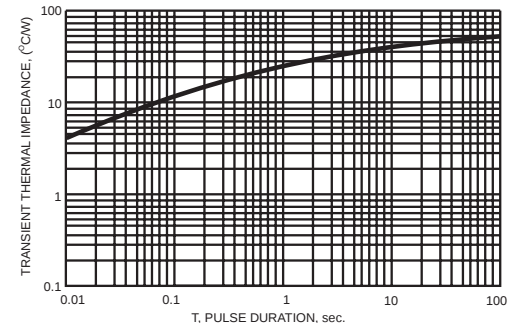
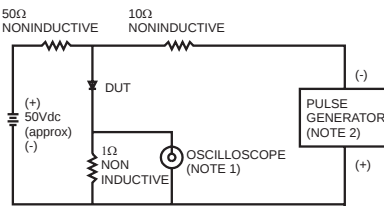
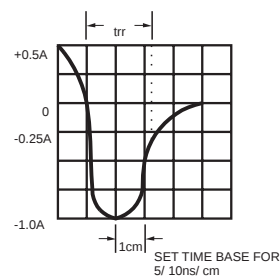


FIG.7- REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM



NOTES: 1. Rise Time=7ns max. Input Impedance=1 megohm 22pf
2. Rise Time=10ns max. Source Impedance=50 ohms



PACKAGE	SPQ/PCS	CARTON SPQ/PCS	CARTON SIZE/CM	CARTON GW/KG	CARTON NW/KG
SMA	5000/REEL	80000	36X30.6X31	12.00	11.00